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dorsaVi Commences Silicon Fabrication of First RRAM-CMOS Validation Chip

Silicon production of dorsaVi's first RRAM-CMOS validation chip has commenced, with the CMOS base now being fabricated ahead of RRAM integration and wafer-level electrical testing

Key Highlights:

- **Silicon manufacturing has commenced:** dorsaVi's first RRAM-CMOS validation chip is now being physically manufactured, with wafer processing underway at the foundry.
- **Design package accepted into the foundry flow:** The manufacturing data package, including design files, mask data, process documentation and wafer-lot instructions, has completed foundry intake and been released into the fabrication sequence.
- **CMOS base now in production:** The current wafer run is producing the front-end CMOS structures that will carry the RRAM memory array, peripheral circuits and test features.
- **Program has moved from data to physical wafers:** Following commencement of tape-out, the validation chip has progressed from design submission and manufacturing preparation into an active wafer run.
- **Key Milestone in RRAM-CMOS Validation Chip Tape-out:** From here, the program will progress through front-end CMOS wafer processing, wafer release for partner-led integration, BEOL preparation, RRAM stack integration and electrical characterisation.
- **Builds towards dorsaVi's RRAM Platform as Critical Memory Infrastructure for the Physical AI Market:** dorsaVi sees its RRAM platform as critical memory infrastructure across exoskeletons, robotics, autonomous systems and IoT edge sensors. Each manufacturing stage also generates process learning that informs future commercialisation from device integration to licensing.

Melbourne, Australia – dorsaVi Limited (ASX: DVL) (“dorsaVi” or the “Company”) is pleased to confirm that manufacturing of its first RRAM-CMOS validation chip has commenced. The chip's manufacturing data package has been accepted into the semiconductor foundry fabrication flow and wafer processing is now underway.

This follows the Company's recently announced commencement of tape-out and marks the point at which the validation chip moves from a design and data-preparation activity into physical silicon production.

Silicon Manufacturing Has Commenced



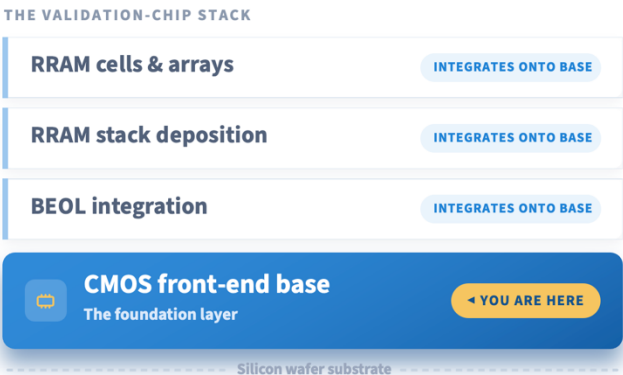
A wafer lot has entered fabrication.

- ✓ Manufacturing data package accepted
- ✓ Wafer lot committed to the fab flow
- ⏻ Wafer processing has started

Foundry acceptance confirms that the validation chip's manufacturing data package has completed the required intake process and has been released into the wafer fabrication sequence. Wafer processing has now started, meaning the physical silicon for the validation chip is being produced.

Entry into a wafer run is a key manufacturing milestone in semiconductor development. It confirms that the design package met foundry intake requirements and that a wafer lot has been committed to the fabrication flow.

What Is Being Manufactured



We're building the layer the **entire RRAM array** is built on.

- ⏻ Foundation layer in fabrication now
- ↑ Every RRAM layer integrates directly onto it
- ⏻ It defines the chip's performance envelope

The current wafer run is producing the front-end CMOS base of the validation chip. This includes the transistor and circuit-level structures that will later support the RRAM memory array, peripheral circuits and evaluation features.

The RRAM-specific steps follow front-end processing. These are expected to include wafer preparation, BEOL integration, RRAM stack deposition, and formation of the integrated RRAM cells and arrays.

Separating the program into defined manufacturing stages allows dorsaVi and its partners to assess progress and generate process learning at each step before electrical validation begins.

Why This Milestone Is Important

01

**Confirms manufacturing intake**
Passed foundry acceptance, removing a key source of early technical risk before wafers are committed.

02

**Creates the CMOS base for integration**
The front-end run produces the structures on which the RRAM stack will later be integrated.

03

**Advances a staged execution pathway**
Each completed step moves the program closer to silicon-level testing and benchmarking.

For dorsaVi, commencement of manufacturing is significant for three reasons:

- Confirms manufacturing intake.** The design package has passed foundry acceptance and entered the wafer fabrication sequence. Confirming the design met the foundry's manufacturability requirements, removes a key source of early-stage technical risk before any wafers are committed.
- Creates the CMOS base required for integration.** The front-end wafer run produces the structures on which the RRAM stack will later be integrated.
- It advances the program on a staged execution pathway.** Each completed manufacturing step reduces execution risk and moves the program closer to silicon-level testing and performance benchmarking.

Commercial Impact on the Physical AI Market



As Physical AI continues to move intelligence out of the cloud and into the device, memory will increasingly become a constrain. This milestone moves dorsaVi a step closer to commercialising the critical memory layer.

Manufacturing converts the RRAM programme from a design into physical silicon that can be tested and shown to partners and customers. It establishes the CMOS foundation dorsaVi's future products are built on, targeting the markets where local, low-power memory is the binding constraint: smart exoskeletons and EMG sensor nodes, robotic joint controllers, autonomous systems such as drones and self-guided vehicles, and always-on IoT edge sensors. And it strengthens dorsaVi's position to move from internal use toward a licensable component for the wider Physical AI hardware market.

Each completed stage also removes technical and execution risk a commercial partner weighs before committing, which supports future supply, partnering and licensing discussions.

Current Program Status

STAGE	STATUS
Design finalisation	✓ Completed
Tape-out commencement	✓ Completed
Foundry acceptance	✓ Confirmed
CMOS base wafer manufacturing	⌚ Underway
CMOS base wafer processing	Next stage
RRAM integration into CMOS base	Subsequent
Electrical testing & characterisation	To follow

The CMOS base serves as the foundation layer that the RRAM will later be added to. Once the base is complete, the wafers move to partner-led processing then integration where the RRAM layer is built on top, followed by testing and performance benchmarking.

CEO Commentary

Mathew Regan, Group Chief Executive Officer of dorsaVi, said:

“Physical AI is moving intelligence out of the cloud and into the device, where systems must sense, decide and act in real time. A critical constraint on that shift is the latency and energy consumed moving data between memory and processing. Our 22-nm RRAM Program with NTU and ITRI is designed to address that constraint by bringing memory and compute closer together.

The current 180-nm validation run is a key stage within that broader program. Commencement of CMOS wafer fabrication moves our first RRAM-CMOS validation chip from completed design into physical implementation and is intended to generate the silicon-level learning required to inform and de-risk our subsequent 22-nm implementation.

The speed, energy efficiency, endurance and non-volatility targeted by the program are the characteristics required by robot joints, exoskeleton nodes and intelligent sensors to make decisions locally rather than sending data to the cloud and waiting for a response. We intend to prove this memory architecture through our own sensing platform and then, subject to successful validation, commercialise it for the wider Physical AI market.”

- ENDS -

This release has been authorised for lodgement to the ASX by the Board.

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Forward-Looking Statements

This announcement may contain certain forward-looking statements and projections. Such forward-looking statements/projections are estimates for discussion purposes only and should not be relied upon. Forward looking statements/projections are inherently uncertain and may therefore differ materially from results ultimately achieved. dorsaVi Limited does not make any representations and provides no warranties concerning the accuracy of the projections and disclaims any obligation to update or revise any forward-looking statements/projections based on new information, future events or otherwise, except to the extent required by applicable laws.

About dorsaVi

dorsaVi Ltd (ASX: DVL) is an ASX company focused on delivering intelligence at the ultra-edge. Enabling real time AI-driven decisions to be made locally, at the point of sensing, without reliance on cloud connectivity. dorsaVi's wearable sensor technology captures, quantifies, and assesses detailed human movement and position outside a biomechanics lab, in both real-time and real situations for up to 24 hours, across clinical applications, elite sports, and occupational health and safety. Underpinning this vision, dorsaVi is building the hardware foundations of the ultra-edge through strategic investments in neuromorphic computing and RRAM memory technology. dorsaVi's focus is on three major markets:

- **Ultra-Edge Intelligence:** dorsaVi's sensor platforms are designed to process and act on data locally, embedding AI-driven inference directly at the point of capture. By investing in neuromorphic computing and RRAM memory technology, dorsaVi enables real-time decision-making without round-tripping to the cloud, delivering lower latency, lower power consumption, and reliable

operation in latency- and connectivity-constrained environments across industrial, clinical, and autonomous systems applications.

- Workplace: dorsaVi enables employers to assess risk of injury for employees as well as test the effectiveness of proposed changes to OHS workplace design, equipment or methods based on objective evidence. dorsaVi works either directly with major corporations, or through an insurance company's customer base with the aim of reducing workplace compensation and claims. dorsaVi has been used by major corporations including London Underground, Vinci Construction, Crown Resorts, Caterpillar (US), Boeing, Monash Health, Coles, Woolworths, Toll, Toyota, Orora, Mineral Resources and BHP.
- Clinical: dorsaVi is transforming the management of patients with its clinical solutions (ViMove+) which provide objective assessment, monitoring outside the clinic and immediate biofeedback. The clinical market is broken down into physical therapy (physiotherapists), hospital in the home and elite sports. Hospital in the home refers to the remote management of patients by clinicians outside of physical therapy (i.e. for orthopaedic conditions). Elite sports refer to the management and optimisation of athletes through objective evidence for decisions on return to play, measurement of biomechanics and immediate biofeedback to enable peak performance.

Further information is available at www.dorsavi.com